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CHEN et al.(10) **Pub. No.: US 2024/0179875 A1**(43) **Pub. Date: May 30, 2024**(54) **SYSTEMS AND METHODS FOR COOLING A
FLUID CIRCUIT FOR COOLING A RACK OF
SERVERS**(71) Applicant: **QUANTA COMPUTER INC.,**
Taoyuan City (TW)(72) Inventors: **Chao-Jung CHEN**, Taoyuan City
(TW); **Yu-Nien HUANG**, Taoyuan City
(TW); **Sin-Hong LIEN**, Taoyuan City
(TW); **Jen-Mao CHEN**, Taoyuan City
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30, 2021.**Publication Classification**(51) **Int. Cl.**
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7/202 (2013.01)(57) **ABSTRACT**

A system includes a rack of servers and a fluid circuit for cooling the rack of servers. The fluid circuit includes one or more cooling modules, a heat-exchanging module, and a pump. The one or more cooling modules are thermally connected to a conduit for flowing a coolant therethrough. Each cooling module includes a heat-exchanger thermally connected to the conduit and a chiller fluidly coupled to the heat-exchanger. The heat-exchanging module is fluidly connected to an outlet of the conduit. The pump is configured to drive the coolant from the heat-exchanging module to each server in the rack of servers.

